

### Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- High Current Capability
- Green Device Available

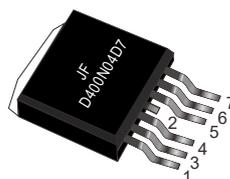
### Applications

- SMPS Synchronous Rectification
- DC/DC Converters
- Or-ing

### Product Summary

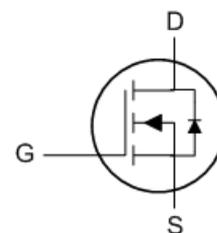
BVDSS	RDSON	ID
40V	1.1mΩ	400A

### TO-263-7L Pin Configuration



Pin Definition:

1. Gate
2. Drain
- 3/4/5/6/7. Source



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)	400	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)	280	A
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Wire Bond Limited)	240	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	1610	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	673	mJ
$I_{AS}$	Avalanche Current	116	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	380	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	40	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.4	$^\circ C/W$

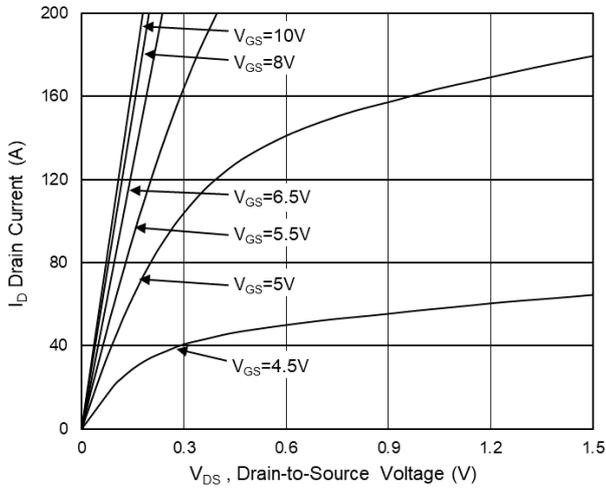
**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =195A	---	0.9	1.1	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	2	2.8	4	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	μA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.2	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	108	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	25.4	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	26.8	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, R <sub>G</sub> =1.5Ω, I <sub>D</sub> =20A	---	20	---	ns
T <sub>r</sub>	Rise Time		---	145	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	55	---	
T <sub>f</sub>	Fall Time		---	18	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz	---	6601	---	pF
C <sub>oss</sub>	Output Capacitance		---	2073	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	248	---	
<b>Diode Characteristics</b>						
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	240	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =195A, T <sub>J</sub> =25°C	---	---	1.2	V

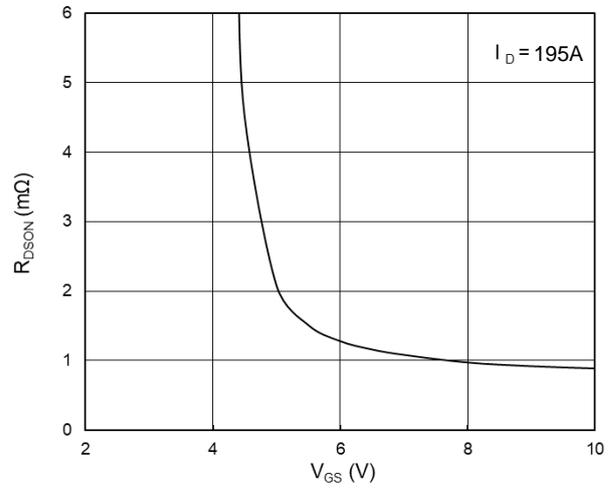
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=240A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.Package limitation current is 240 A.

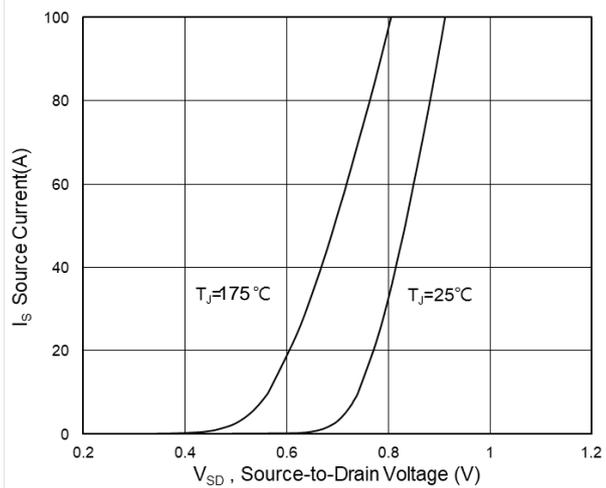
## Typical Characteristics



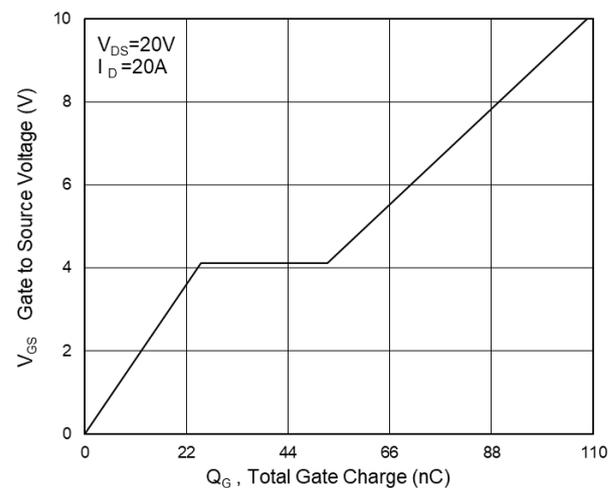
**Fig.1 Typical Output Characteristics**



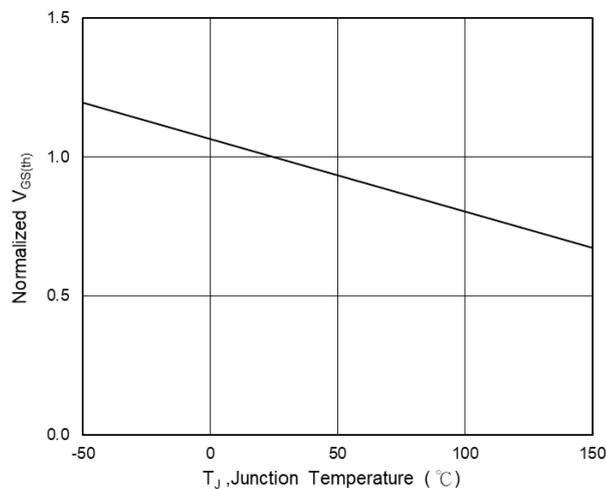
**Fig.2 On-Resistance vs G-S Voltage**



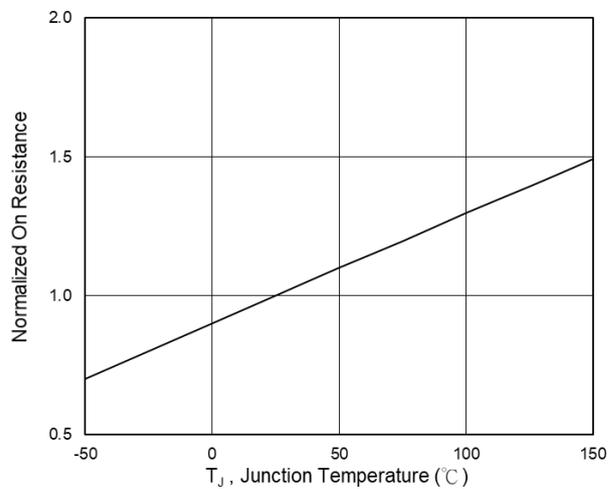
**Fig.3 Source Drain Forward Characteristics**



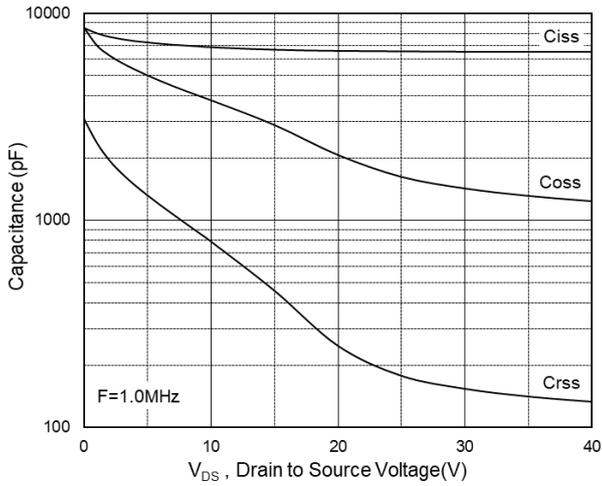
**Fig.4 Gate-Charge Characteristics**



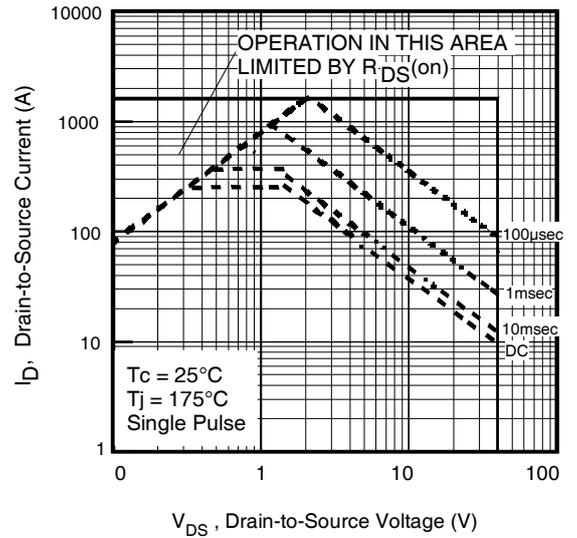
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



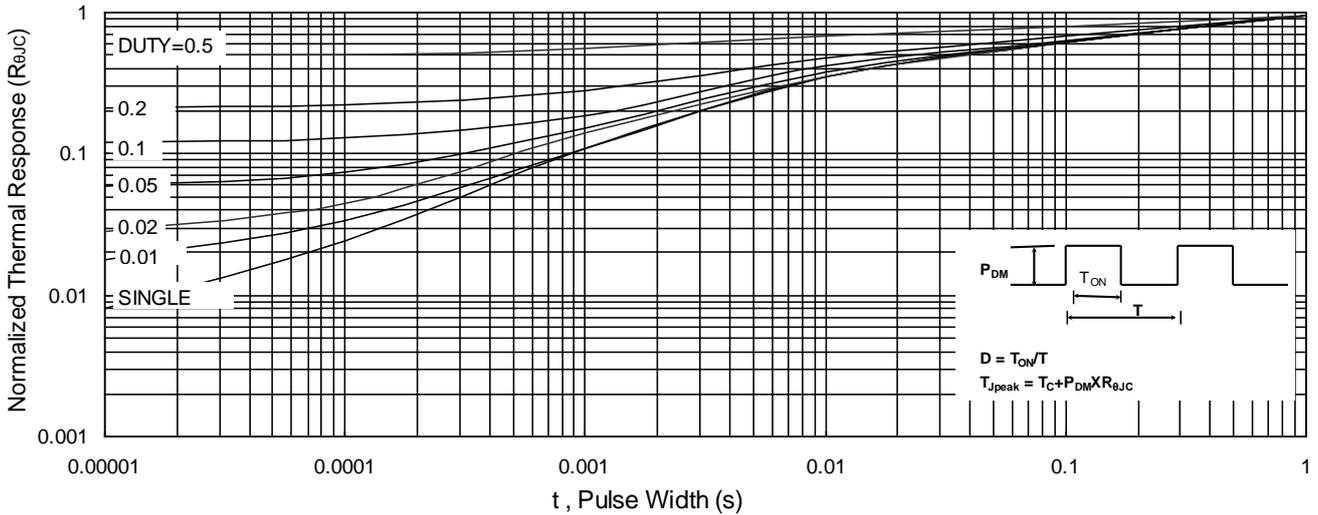
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



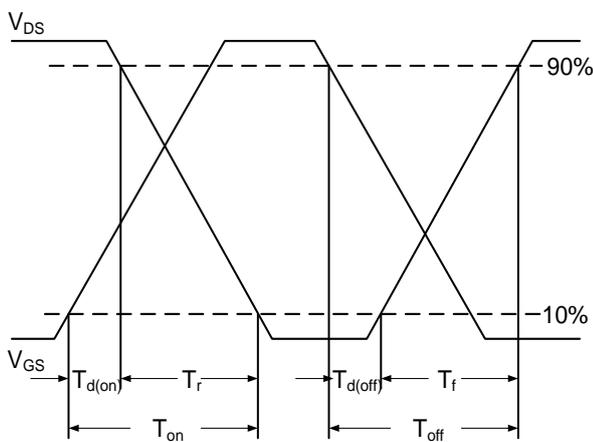
**Fig.7 Capacitance**



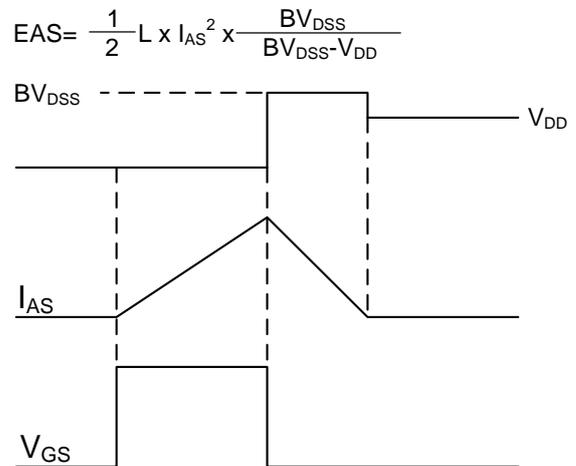
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

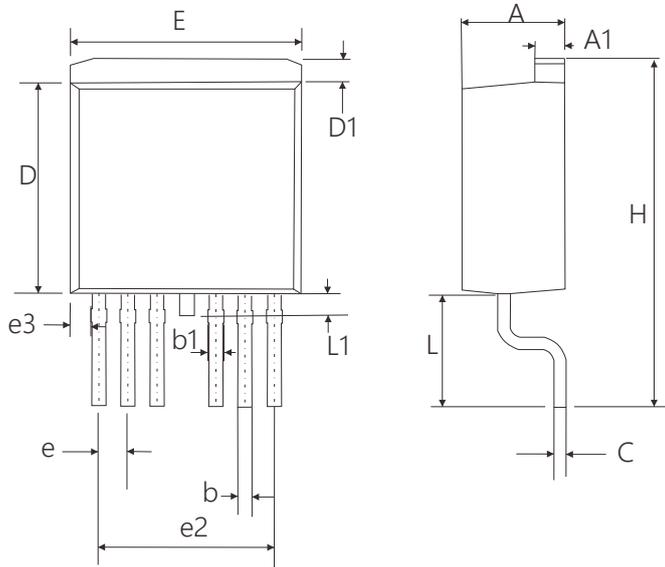


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

# TO-263-7L Outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	4.25	4.75	0.167	0.187
A1	1.2	1.4	0.047	0.055
b	0.5	0.7	0.020	0.028
b1	0.5	0.9	0.020	0.035
C	0.4	0.6	0.016	0.024
D	9.05	9.45	0.356	0.372
D1	0.7	1.3	0.028	0.051
E	9.8	10.2	0.386	0.402
e	1.07	1.47	0.042	0.058
e2	7.32	7.92	0.288	0.312
e3	0.64	1.04	0.025	0.041
H	14.65	15.65	0.577	0.616
L	4.47	5.47	0.176	0.215
L1	0.90	1.50	0.035	0.059

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